

DATASHEET

SMD • B 19-337/R6GHBHC-A01/2T



Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Full-color type.
- Pb-free
- The product itself will remain within RoHS compliant version.

Description

- The 19-337 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.



Device Selection Guide

Code	Chip Materials	Emitted Color	Resin Color
R6	AlGaInP	Brilliant Red	
GH	InGaN	Brilliant Green	Water Clear
ВН	InGaN	Blue	_



Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Code	Rating	Unit
Reverse Voltage	V _R		5	V
Forward Current	l _F		25	mA
	I _{FP}	R6	60	
Peak Forward Current (Duty 1/10 @1KHz)		GH	100	mA
		ВН	100	_
		R6	60	
Power Dissipation	Pd	GH	95	mW
		ВН	95	_
		R6	2000	
Electrostatic Discharge(HBM)	ESD	GH	150	
		ВН	150	_
Operating Temperature	T_{opr}		-40 ~ +85	$^{\circ}\! C$
Storage Temperature	Tstg		-40 ~ +90	$^{\circ}\! C$
Soldering Temperature	Tsol		Reflow Soldering : 26 Hand Soldering : 350	



Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Code	Min.	Тур.	Max.	Unit	Condition
		R6	72.0	100	225	_	
Luminous Intensity	lv	GH	140	180	285	mcd _	
		ВН	36.0	50.0	90.0		
Viewing Angle	$2\theta_{1/2}$			120		Deg	_
		R6		632		_	
Peak Wavelength	λр	GH		518		nm	
		ВН		468			_
	λd	R6	614	624	628		
Dominant Wavelength		GH	518	525	528	nm	I _F =20mA
. ravolongan		ВН	465	470	475	_	
	Δλ	R6		20			
Spectrum Radiation Bandwidth		GH		35		nm	
		ВН		25		_	
Forward Voltage	V _F	R6	1.7		2.4		
		GH	2.7		3.8	V	
		ВН	2.7		3.8	_	
Reverse Current	I _R	R6			10		V _R =5V
		GH			50	μA	
		ВН			50		

Note:

^{1.} Tolerance of Luminous Intensity: ±11%

^{2.} Tolerance of Dominant Wavelength: ±1nm

^{3.} Tolerance of Forward Voltage: ±0.1V



R6

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
Q1	72.0	90.0		
Q2	90,0	112		
R1	112	140	mcd	I _F =20mA
R2	140	180		
S1	180	225		

GH

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
R2	140	180		
S1	180	225	mcd	I _F =20mA
S2	225	285	<u></u>	

BH

Bin Range of Luminous Intensity

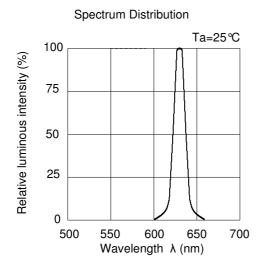
Bin Code	Min.	Max.	Unit	Condition
N2	36.0	45.0		
P1	45.0	57.0		L 00 × A
P2	57.0	72.0	mcd	I _F =20mA
Q1	72.0	90.0	<u>.</u>	

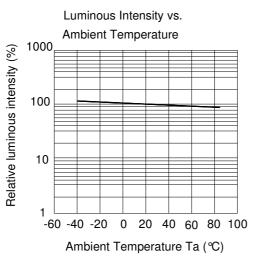
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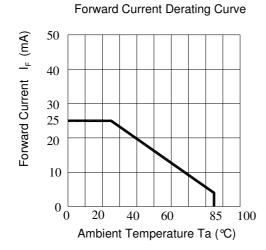
Tolerance of Luminous Intensity: ±11%

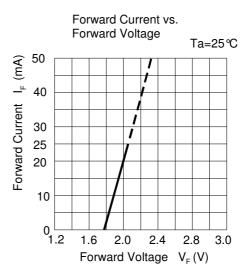
Typical Electro-Optical Characteristics Curves

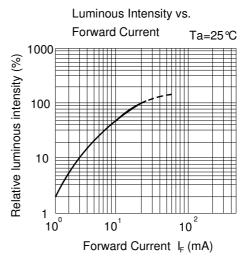
R6

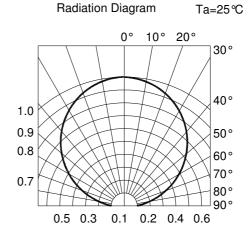








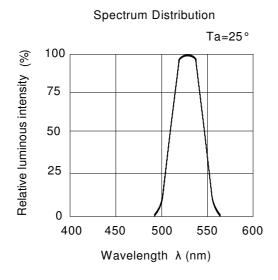


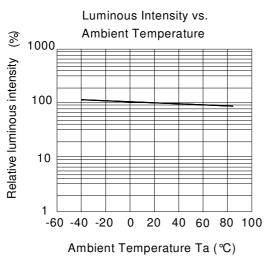


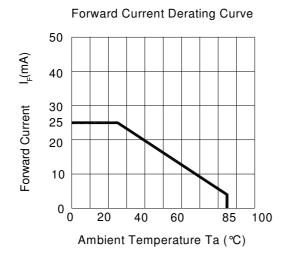


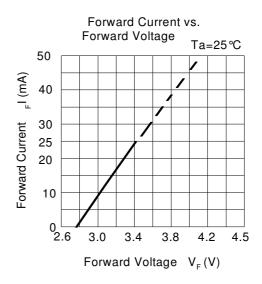
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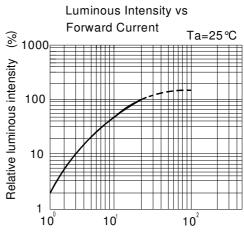
GH



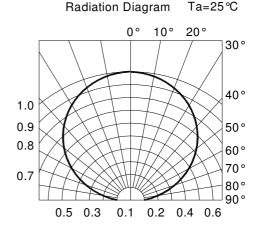






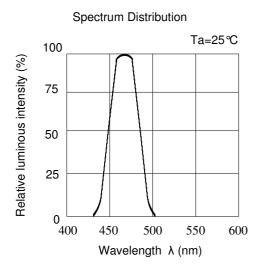


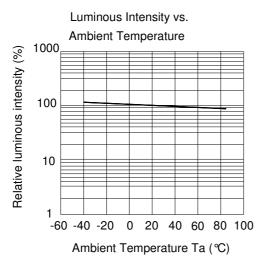
Forward Current I_F(mA)

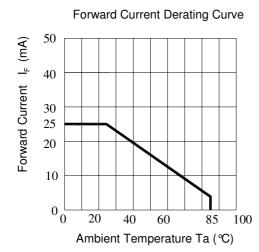


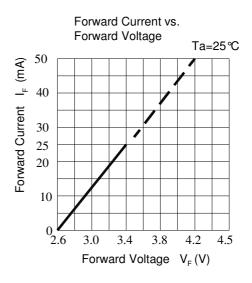
Typical Electro-Optical Characteristics Curves

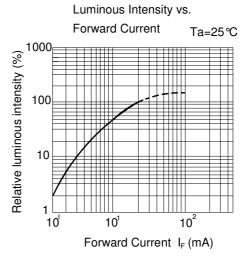
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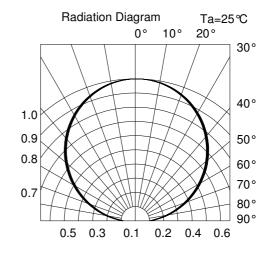






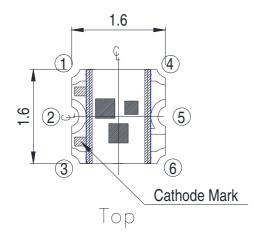


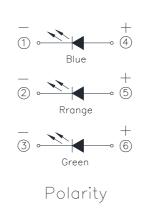


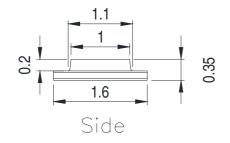




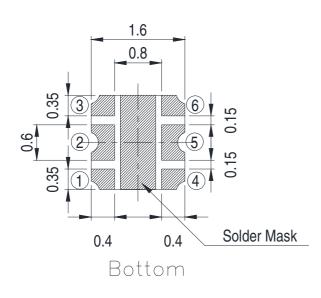
Package Dimension

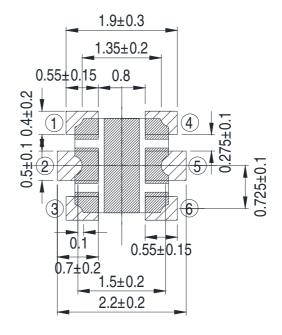












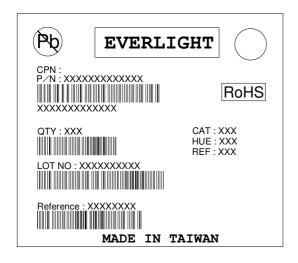
Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need

Note: Tolerances unless mentioned ±0.1mm. Unit = mm



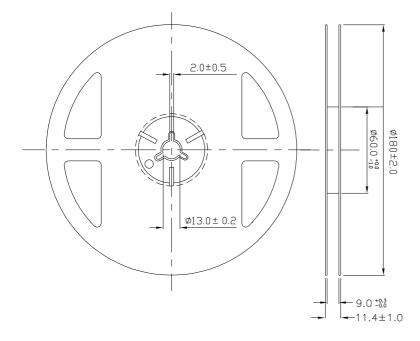
Moisture Resistant Packing Materials

Label Explanation



- · CPN: Customer's Product Number
- P/N: Product Number
- · QTY: Packing Quantity
- · CAT: Luminous Intensity Rank
- · HUE: Chromaticity Coordinates & Dom. Wavelength Rank
- REF: Forward Voltage Rank
- · LOT No: Lot Number

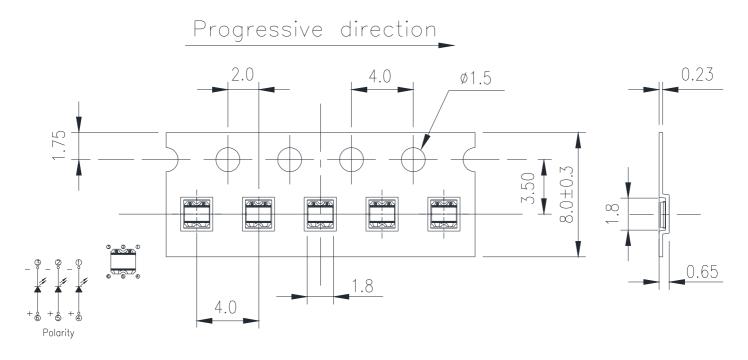
Reel Dimensions



Note: The tolerances unless mentioned is $\pm 0.1 \text{mm}$, Unit = mm

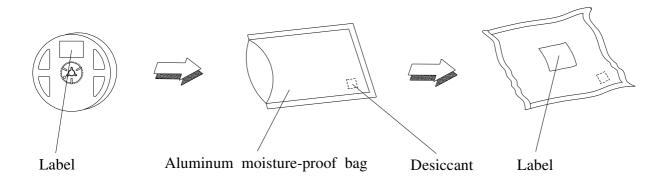


Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Moisture Resistant Packaging





Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

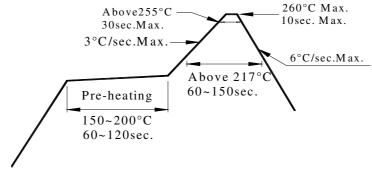
- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 1 year under 30° or less and 60% RH or less.

If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: $60\pm5^{\circ}$ C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



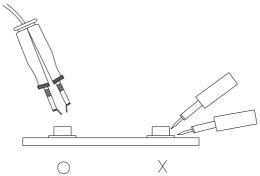
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.





Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.